

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	103	("20010020545" "20020027022" "4295700" "4297312" "4867042" "4876042" "4916002" "4949455" "4968585" "5101553" "5317255" "5338178" "5345365" "5418471" "5475318" "5478779" "5484964" "5686317" "5789140" "5795162" "5820014" "5834945" "5860818" "5915977" "5926375" "5939817" "5994152" "6033935" "6049976" "6059982" "6078186" "6107109" "6114240" "6232143" "6242803" "6246245" "6255126" "6294837" "6300780" "6356098" "6426638" "6462575" "6475822" "6491968" "6520778" "6525555" "6767219" "6814584" "6830460" "6871307" "6897666" "6953348" "RE00000").PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/03/13 16:03
L2	203	324/761,762.ccls. and (compliant or elastomer\$3)	US-PGPUB; USPAT; USOCR	OR	OFF	2007/03/13 18:18
L3	1	"20050229393"	US-PGPUB; USPAT; USOCR	OR	OFF	2007/03/13 17:52
L4	1	"20050230811"	US-PGPUB; USPAT; USOCR	OR	OFF	2007/03/13 18:12
L5	4	((("5421763") or ("5926029") or ("5483741") or ("6016060")).PN.	USPAT	OR	OFF	2007/03/13 18:13
L6	4	((("5821763") or ("5926029") or ("5483741") or ("6016060")).PN.	USPAT	OR	OFF	2007/03/13 18:14
L7	1	("6767219").PN.	USPAT	OR	OFF	2007/03/13 18:14
L8	2	((("5686317") or ("6778406")).PN.	USPAT	OR	OFF	2007/03/13 18:15
L9	1	("6767219").PN.	USPAT	OR	OFF	2007/03/13 18:15
L10	2	((("5625298") or ("6630839")).PN.	USPAT	OR	OFF	2007/03/13 18:15
L11	3	"6953348"	US-PGPUB; USPAT; USOCR	OR	OFF	2007/03/13 18:19
L12	11	re27089	US-PGPUB; USPAT; USOCR	OR	OFF	2007/03/13 18:19

JR = inter-lateral search

U.S. Patent

Jul 1, 2003

Sheet 6 of 6

US 6,586,955 B2

FIG. 19

134, 122, 126, 124, 132, 118, 130, 148, 136, 110, 112, 144, 146, 150, 150, 140, 142

US-PAT-NO: 6586955

DOCUMENT-IDENTIFIER: US 6586955 B2

See image for Certificate of Correction

TITLE: Methods and structures for electronic probing arrays

Detailed Description Text - DETX (14):

The flowable material used to form compliant layer 128 should be capable of flowing, prior to cure, at temperatures below the melting temperature of the ULMS of core elements 118. To assure complete filling of space by the flowable material, the flowable material may be injected under pressure. Also, the space may be evacuated prior to injection of the flowable material. Techniques for evacuation of a space between a flexible sheet and wafer and for injection of flowable, curable materials into such a space are further disclosed in International Patent Publication No. 96/02068 and U.S. Pat. No. 5,913,109, both of which are incorporated herein by reference. Suitable flowable materials for forming the compliant layer 128 include polymer compositions which are initially in the form of liquids but which cure by chemical reaction of their ingredients to form a solid or gel. Among the compositions that can be used are silicones, epoxies and urethanes. Particularly suitable compositions include silicone elastomers of the type sold under the designation Sylgard.RTM. 577 by the Dow Corning Corporation of Midland, Mich., Dow Corning.RTM. 6811 microelectronic encapsulant and flexibized epoxies. The reaction-curable material may be provided as two mutually reactive components which are mixed immediately prior to introduction of the material into the space and which react spontaneously with one another at ambient temperature. Other reactive polymer compositions can be activated by application of ultraviolet light. The curing step can also be initiated or accelerated by heating the reactive polymer composition. Some or all of the curing step may entail temperatures above the melting temperature of the fusible material in core elements 118.

Current US Cross Reference Classification - CCXR (1):

324/761

Details

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FOR
10/791,195

U.S. Patent Oct. 24, 2006 Sheet 2 of 2 US 7,126,364 B2

FIG. 5

FIG. 6

US-PAT-NO: 7126364

DOCUMENT-IDENTIFIER: US 7126364 B2

TITLE: Interface comprising a thin PCB with protrusions for testing an integrated circuit

DATE-ISSUED: October 24, 2006

PRIOR-PUBLICATION-INFORMATION: DOCUMENT-IDENTIFIER: US 20060033511 A1; DOCUMENT-DATE: February 16, 2006

INVENTOR-INFORMATION: NAME: Jardin-Lemagnen; Free; Savin; Emmanuel; Leruez; Se; CITY: Caen; Soulangy; Caen; STATE: N/A; N/A; ZIP CODE: N/A; N/A; COUNTRY: FR; FR

ASSIGNEE INFORMATION: NAME: Koninklijke Philips Electronics, N.V.; CITY: Eindhoven; STATE: N/A; ZIP CODE: N/A; COUNTRY TYPE CODE: NL 03

APPL-NO: 10/527108; DATE FILED: September 4, 2003

FOREIGN-APPL-PRIORITY-DATA: COUNTRY APPL-NO APPL-DATE; FR 02 11243 September 11, 2002

PCT-DATA: APPL-NO: 03899; DATE-FILED: September 4, 2003; PUB-NO: W020/04/025309; PUB-DATE: Mar 25, 2004; 371-DATE: Mar 8, 2005

INT-CL-ISSUED: TYPE: FULL; IPC DATE: FULL; IPC-OLD: FULL

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testing methods for method for conductor system using

For 10/791, 195

U.S. Patent

Feb. 25, 1992

Sheet 3 of 3

5,090,118

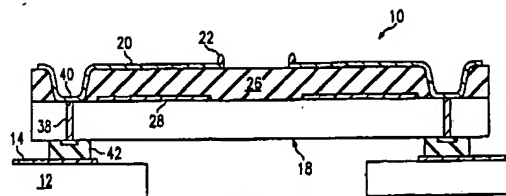


FIG. 6

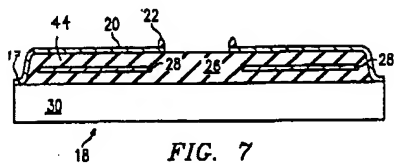


FIG. 7

US-PAT-NO: 5090118

DOCUMENT-IDENTIFIER: US 5090118 A

TITLE: High performance test head and method of making

DATE-ISSUED: February 25, 1992

INVENTOR-INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY
Kwon, On-Ryong	Plano	TX	N/A	N/A
Hashimoto, Masashi	Garland	TX	N/A	N/A
Malhi, Satwinder	Garland	TX	N/A	N/A

ASSIGNEE INFORMATION:

NAME	CITY	STATE	ZIP CODE	COUNTRY	TYPE CODE
Texas Instruments Incorporated	Dallas	TX	N/A	N/A	02

APPL-NO: 07/560398

DATE FILED: July 31, 1990

PARENT-CASE:

RELATED APPLICATIONS

The present invention relates to the invention disclosed and claimed in the application Ser. No. 560,404, entitled "DISPOSABLE HIGH PERFORMANCE TEST HEAD" by Aton et al, filed July 31, 1990, and Ser. No. 745,994 entitled "COMPLAINT CONTACT PAD" by Kwon et al, filed Aug. 9, 1991 which is a continuation of Ser. No. 560,936, filed July 31, 1990. Each of these applications are assigned to TEXAS INSTRUMENTS INCORPORATED of DALLAS, TEX.

INT-CL-ISSUED: [05] H01R009/06, B01R001/00

INT-CL-CURRENT:

TYPE	IPC DATE
CIPS	G01 R 31/28 20060101
CIPS	G01 R 1/073 20060101

US-CL-ISSUED: 29/843, 29/846, 324/158P

Details	Text	Image	HTML	FULL
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US	NO	DATE	CLASS	DESCRIPTION	CLASS
US 4980635 A	19901225	5	testing integrated circuits		
US 4975638 A	19901204	10	Integrated circuit package carrier	324/	
US 4963225 A	19901016	5	Test probe assembly for testing integrated circuit	324/	
US 4956604 A	19900911	10	Method of fabricating a contact device	216/	
			Broad band contactor	324/	

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10/79/195